

ABSTRACT OF THE DISCLOSURE

Stabilizers for placement on a surface of a semiconductor device component and methods for fabricating and placing the stabilizers on semiconductor device components. Upon assembly of the semiconductor device component face down upon a higher level substrate and joining conductive structures between the contact pads of the semiconductor device component and corresponding contact pads of the higher level substrate, the stabilizers at least partially stabilize the semiconductor device component on the higher level substrate to prevent tilting or tipping of the semiconductor device component relative to the higher level substrate. The stabilizers can also be positioned and configured to define a minimum, substantially uniform distance between the semiconductor device component and the higher level substrate. The stabilizers may be either preformed structures or formed on the surface of the semiconductor device component. A stereolithographic method of fabricating the stabilizers is disclosed.

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